



Material Content Data Sheet



Sales Product Name		ESD5V3U2U-03F H6327		Issued		20. July 2018		
MA#		MA001293348						
Package		PG-TSFP-3-1		Weight*		1.44 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.05		485	
	noble metal	gold	7440-57-5	0.003	0.19		1883	
	inorganic material	silicon	7440-21-3	0.020	1.40	1.64	13950	16318
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		80	
	non noble metal	titanium	7440-32-6	0.001	0.04		399	
	non noble metal	chromium	7440-47-3	0.002	0.12		1196	
	non noble metal	copper	7440-50-8	0.570	39.71	39.88	397058	398733
wire	noble metal	gold	7440-57-5	0.005	0.35	0.35	3515	3515
encapsulation	organic material	carbon black	1333-86-4	0.008	0.54		5408	
	plastics	epoxy resin	-	0.167	11.63		116270	
	inorganic material	silicondioxide	60676-86-0	0.602	41.90	54.07	419111	540789
leadfinish	non noble metal	tin	7440-31-5	0.033	2.33	2.33	23306	23306
plating	noble metal	silver	7440-22-4	0.025	1.73	1.73	17339	17339
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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